Accelerating Sustainable Composite Manufacturing

Dielectric Sensors and Machine Learning

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EXPAND your sense of the possible

sensXPERT Introduction



Parent Company: **NETZSCH**

Founded: **1962** (Analyzing and Testing)

Global scientific instrument and thermal analysis leader with 4100+ employees present in 36 countries



Corporate Venture: NETZSCH Process Intelligence GmbH

Founded: **2019**

Technology startup developing intelligent manufacturing solutions

sensXPERT Digital Mold



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3. cloud service and customizable dashboards

In-Mold Thermal Analysis

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Material Knowledge at the Heart of Process Enhancement

Real-Time Material Characterization with Dielectric Sensors

- Measuring material behavior
 - resin viscosity, degree of cure, glass-transition, material condition (mixing ratio, ageing, shrinkage, contamination)
- Combined with third-party measurement devices (pressure transducers, thermocouples, and more)

MATERIALS

- Thermosets and thermoplastics
- Fiber reinforced polymers
- Mineral casting

PROCESSES

- (Reaction) Injection Molding
- Compression Molding
- Resin Transfer Moulding Processes
- Autoclave Curing

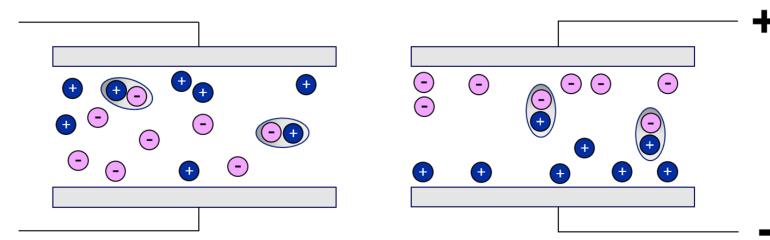
Dielectric Analysis

- Observes the behavior of material under the application of an electric field
- Molecules in the material sample have a net electric charge
- Interact with the electric field
- Ion viscosity An analog to mechanical viscosity

Behavior of ions and dipoles inside an external electrical field

Without external electrical field

With external electrical field



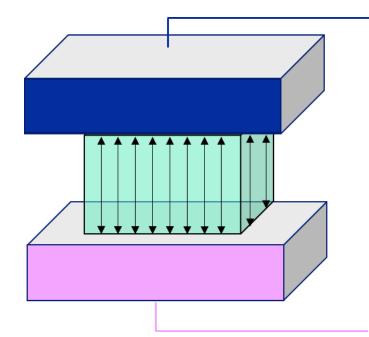
Dielectric Analysis

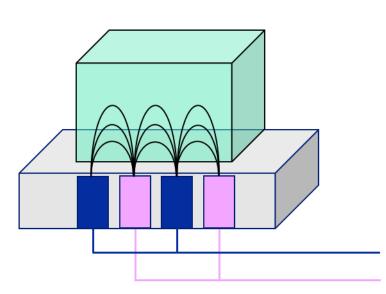
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Traditional parallel plate electrodes

Interdigitated "comb" electrodes

sensXPERT in-mold sensor





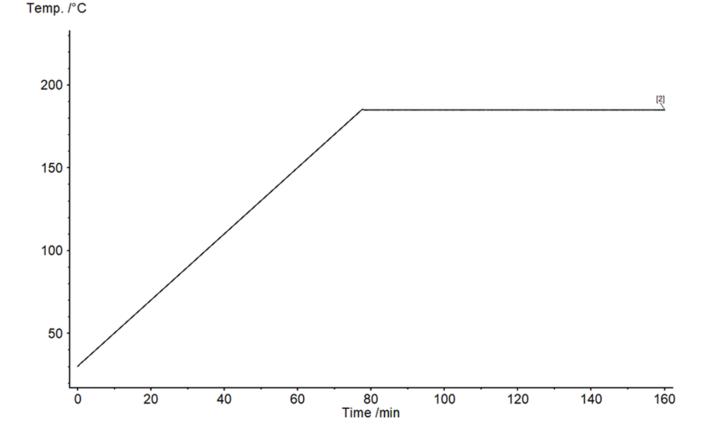


RTM / Infusion Epoxy

180 °C / 350 °F mono-component epoxy system

Standard process data

- Temperature ramp
- Holding time
- No viscosity or cure information



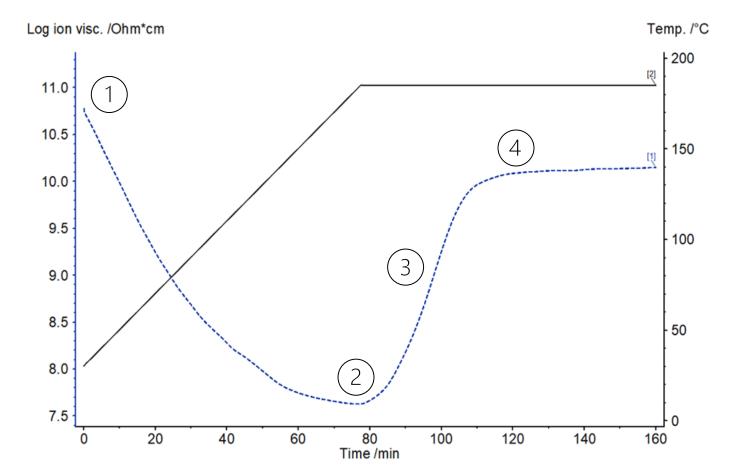
RTM / Infusion Epoxy

180 °C / 350 °F mono-component epoxy system

sensXPERT process data

- Introduction of the material
-) Minimum resin viscosity
- Progression of cure / gelation
- Completion of cure

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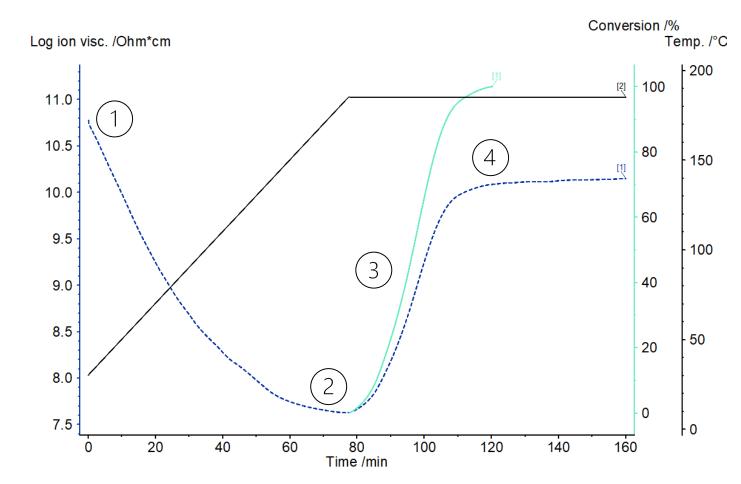
RTM / Infusion Epoxy

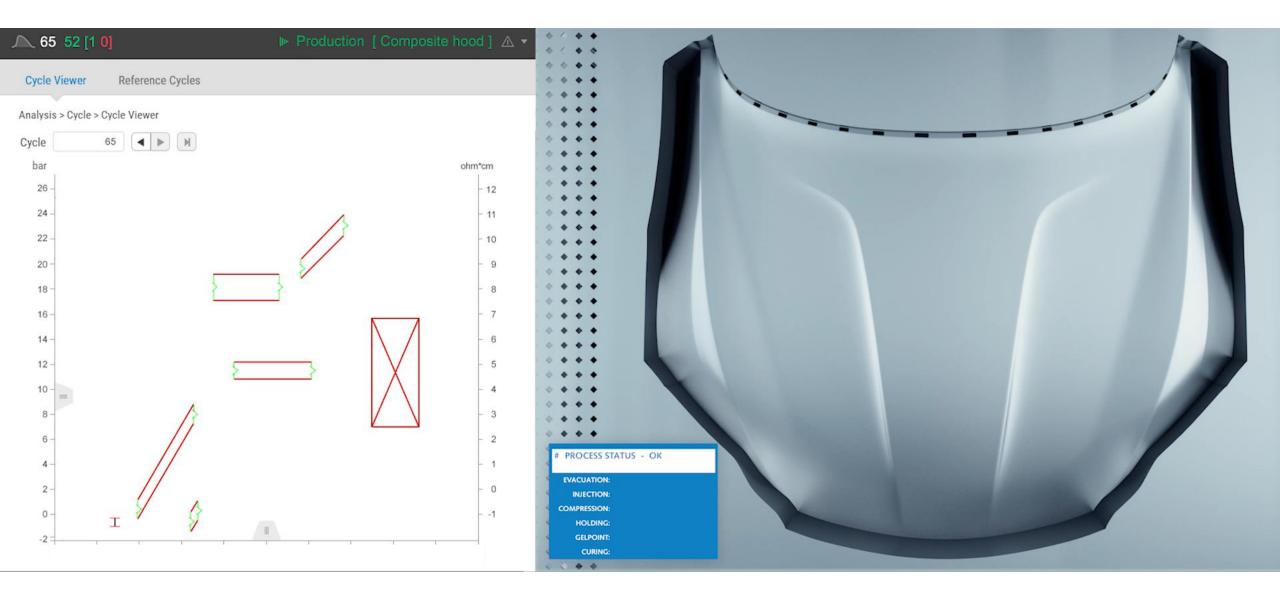
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sensXPERT process data

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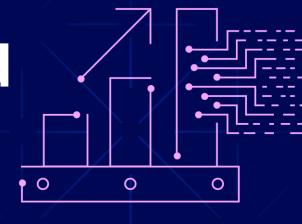
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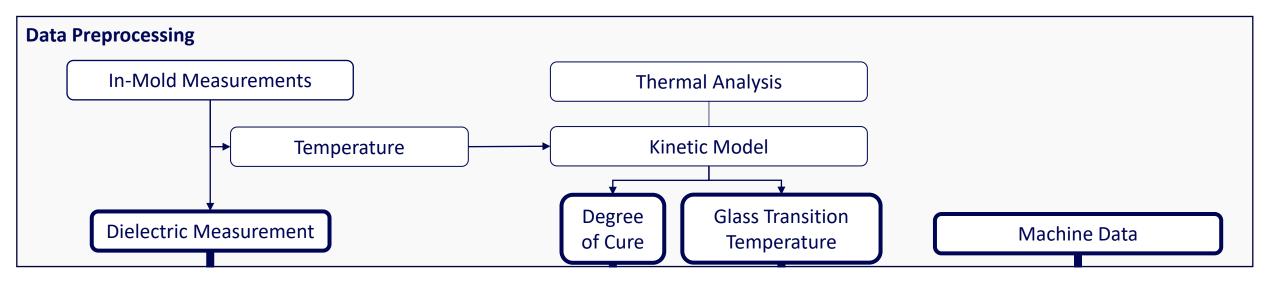
Process Predictions and Optimization







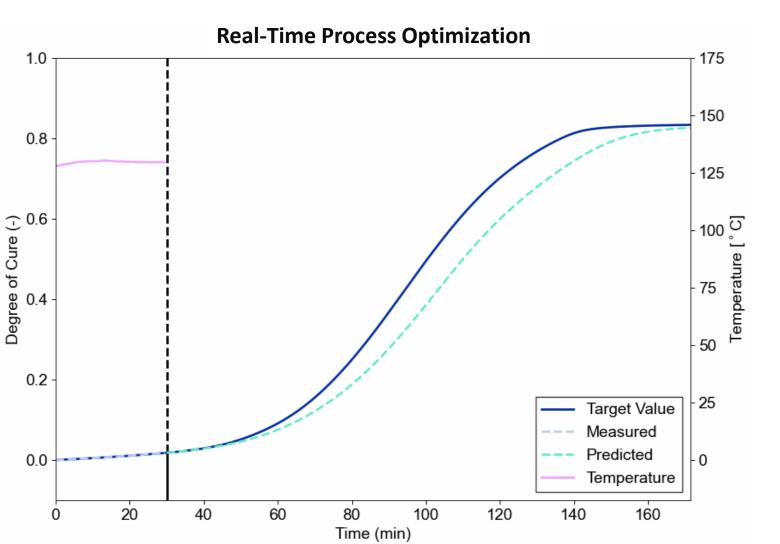
Machine Learning and Process Optimization



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Simulation and Optimization



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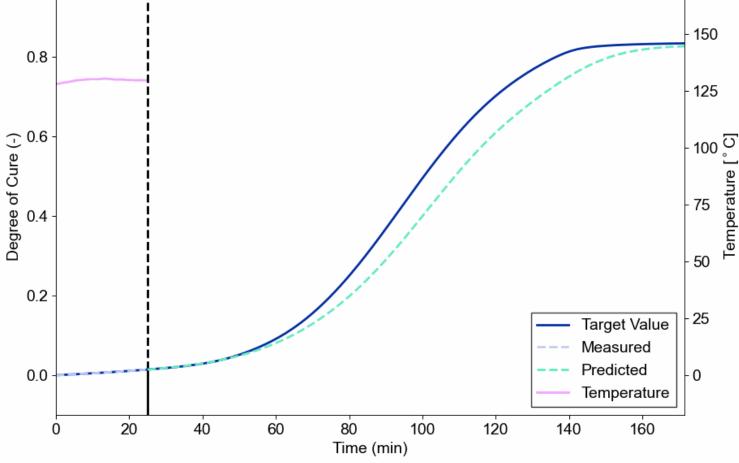
Simulation and Optimization

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A data driven solution.

- AI model calculates and predicts • material properties
- Dynamically control and adapt the ٠ process to ensure constant quality

Real-Time Process Optimization

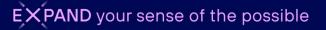


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Process Monitoring and Customized Dashboards





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Cloud Service

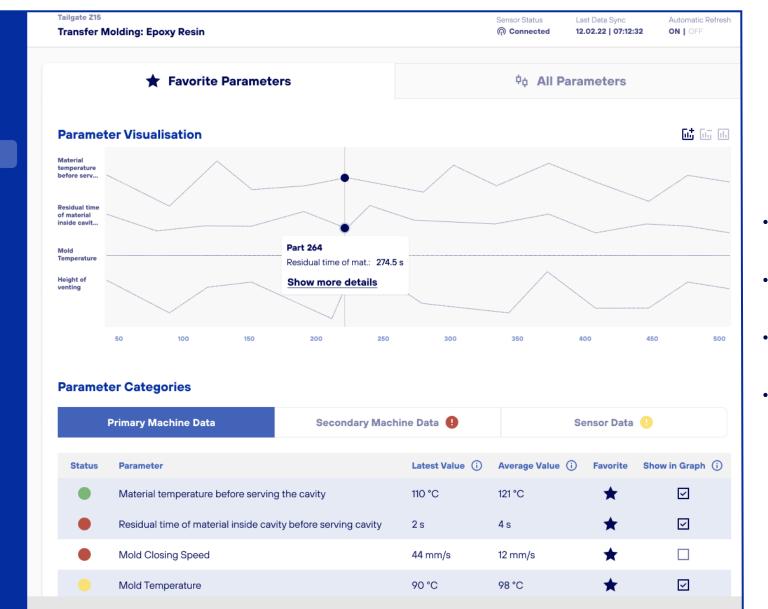


Tailgate Z15

- Compression Molding
- Ø Injection Molding
- Engine Cover sensX
 - Transfer Molding
 - Ø Injection Molding
- Bumber Bar U76
 - Ompression Molding
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Data History
 Settings

⊖ Logout



Company Info / Legal Notice

Terms of Delivery and Payment

Privacy Policy

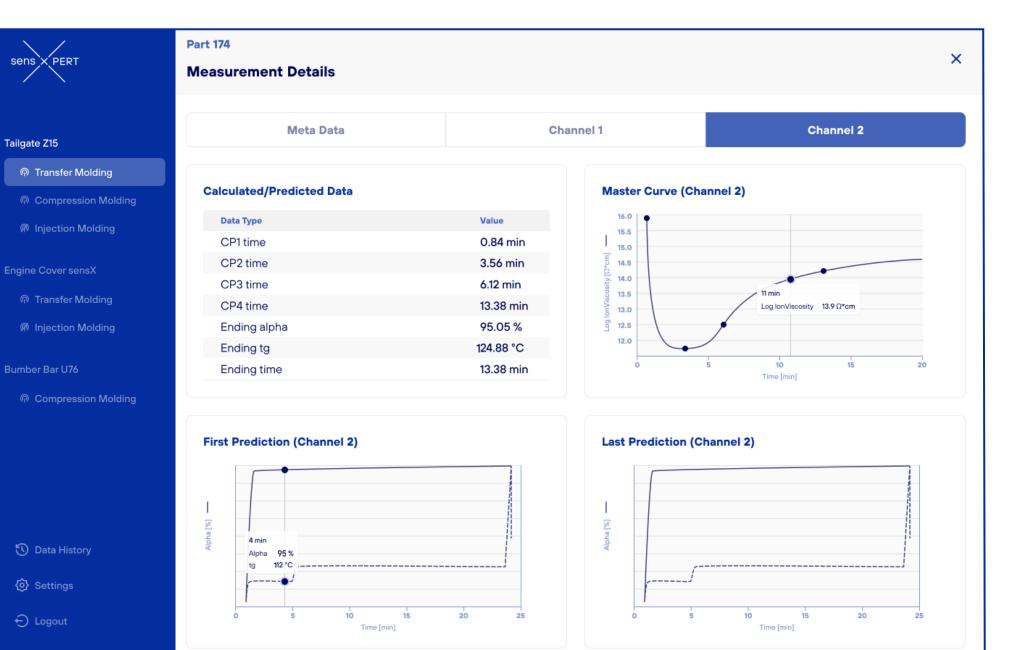
- Process transparency
- 24/7 access on any device
- Customizable dashboards
- OpenAPI: flexible data handling

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Cloud Service





INDUSTRIES WE WORK WITH





Electronics Encapsulation

Use Case





OPTIMIZING ELECTRONICS ENCAPSULATION FOR E-MOBILITY



<u>Component:</u> High-power electronics circuit board

Material: Epoxy molding compound

<u>Quality criterion:</u> Degree of cure > 90%

Target cycle time: 3 minutes



OPTIMIZING ELECTRONICS ENCAPSULATION FOR E-MOBILITY

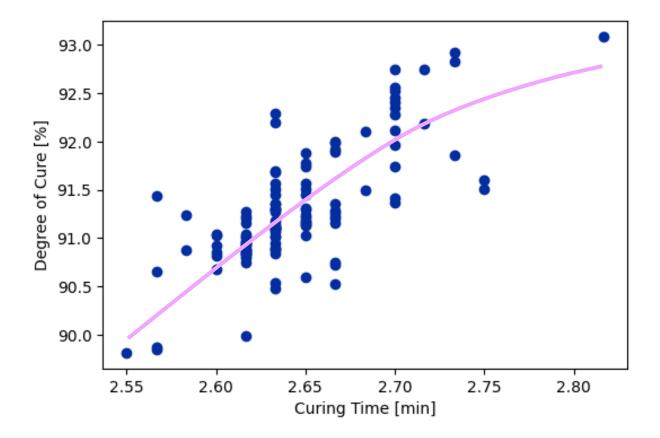


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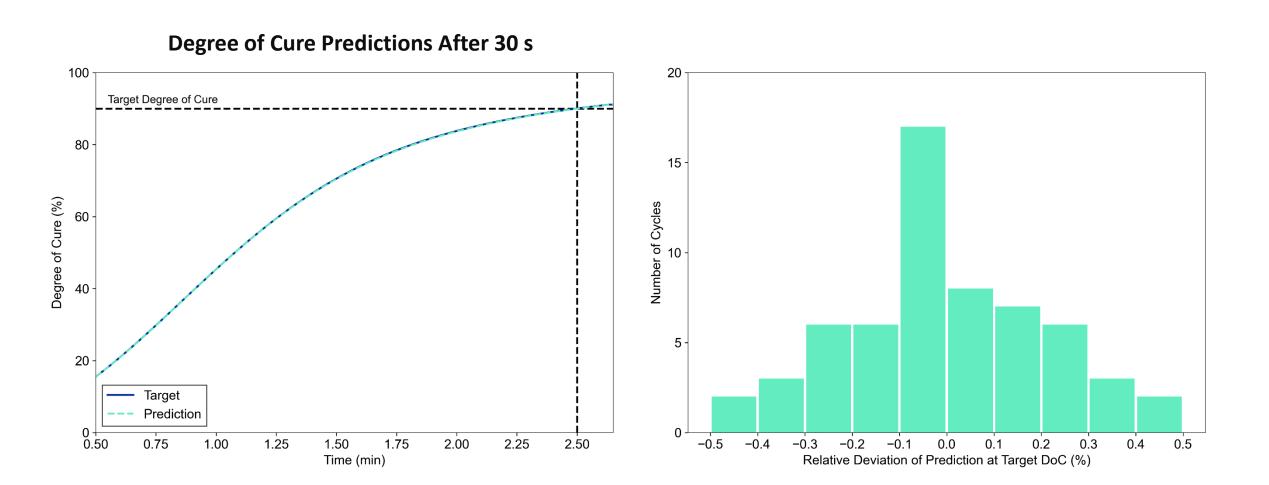
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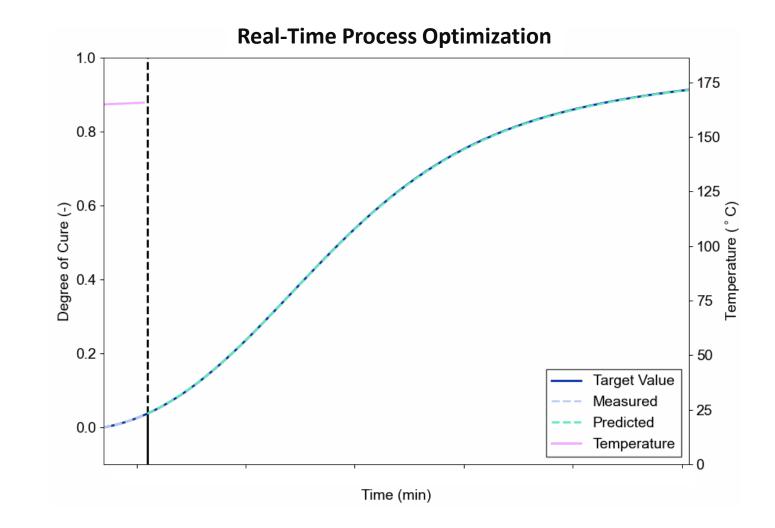
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OPTIMIZING ELECTRONICS ENCAPSULATION FOR E-MOBILITY

Dynamic Process Optimization

- Actively control process to reduce cure deviation by 50%
- Up to **10%** reduction in cycle time
- Improved automation



CosiNo Composites for Sustainable Mobility

Contraction of the

- Thermoplastic RTM
- Digitized composites processing
- Sensor-based quality control





sensXPERT Use Case:

T-RTM FOR AUTOMOTIVE COMPOSITE BATTERY ENCLOSURE



<u>Component:</u> Automotive composite battery enclosure

Material: Polyamide 6, glass fiber, carbon fiber

<u>Quality criterion</u>: Degree of polymerization > 90%

Target cycle time: 10 minutes





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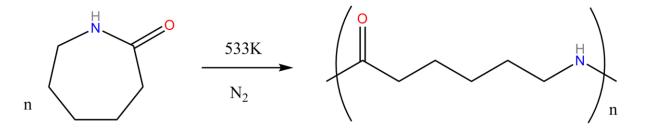
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Thermoplastic Resin Transfer Molding In-Situ Polymerization

ε-Caprolactam

Polyamide 6



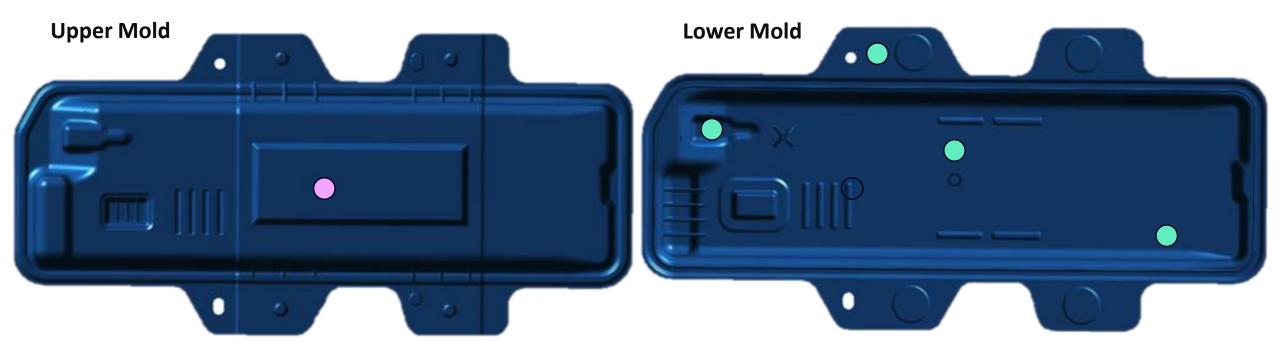
source: wikipedia.org



sensXPERT Use Case:

T-RTM FOR AUTOMOTIVE COMPOSITE BATTERY ENCLOSURE



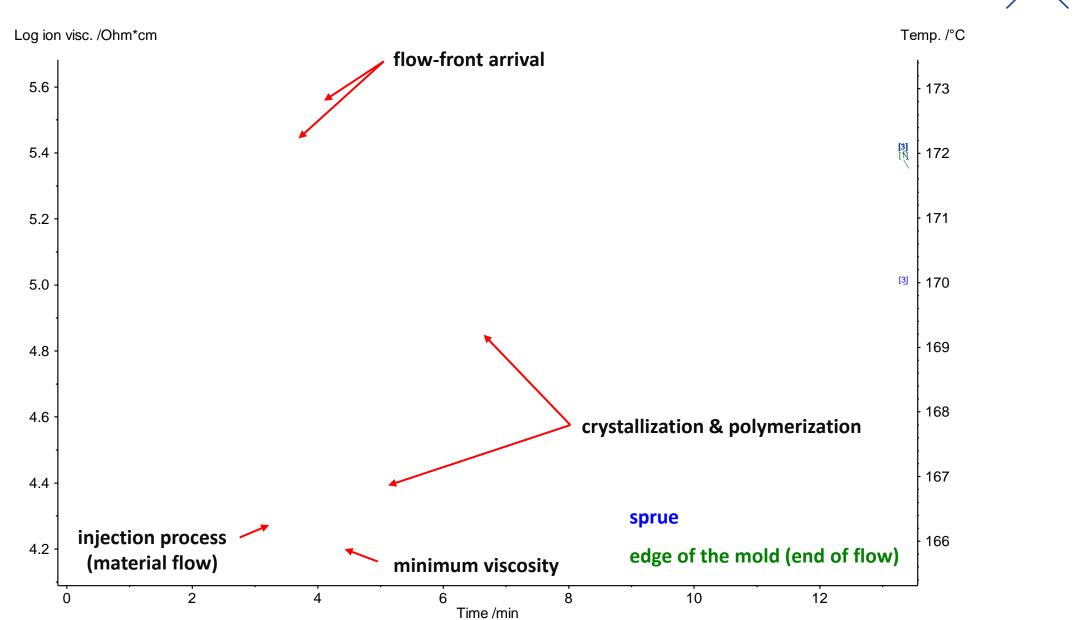


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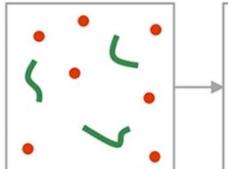


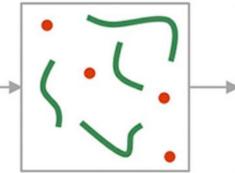
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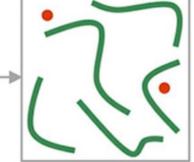


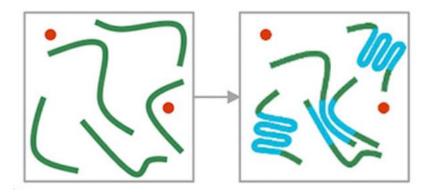
Polymerization & Crystallization







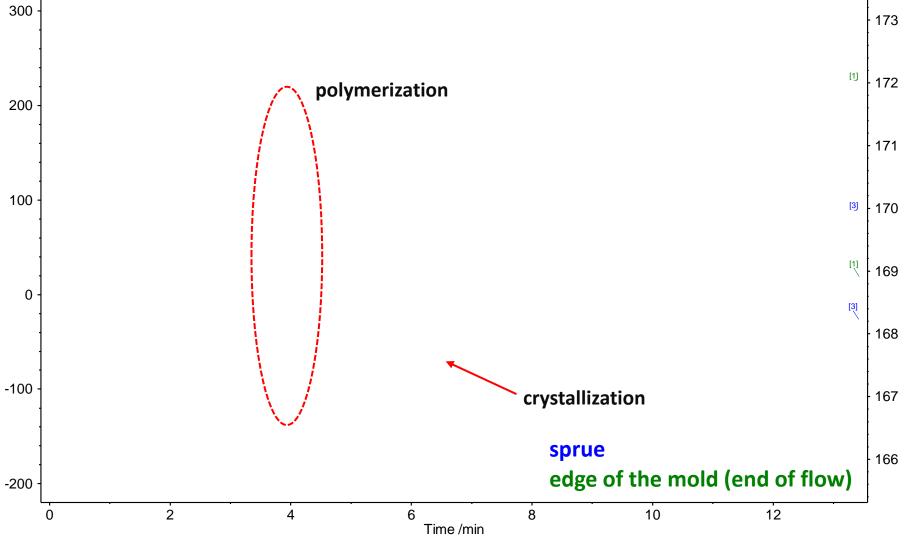




Pictures from: Céline Vicard, Olivier De Almeida, Arthur Cantarel, Gérard Bernhart, *Experimental study* of polymerization and crystallization kinetics of polyamide 6 obtained by anionic ring opening polymerization of ε-caprolactam, Polymer, Volume 132, 2017, Pages 88-97.



sens X PERT Temp. /°C 173 [1] 172 polymerization 171 [3] 170



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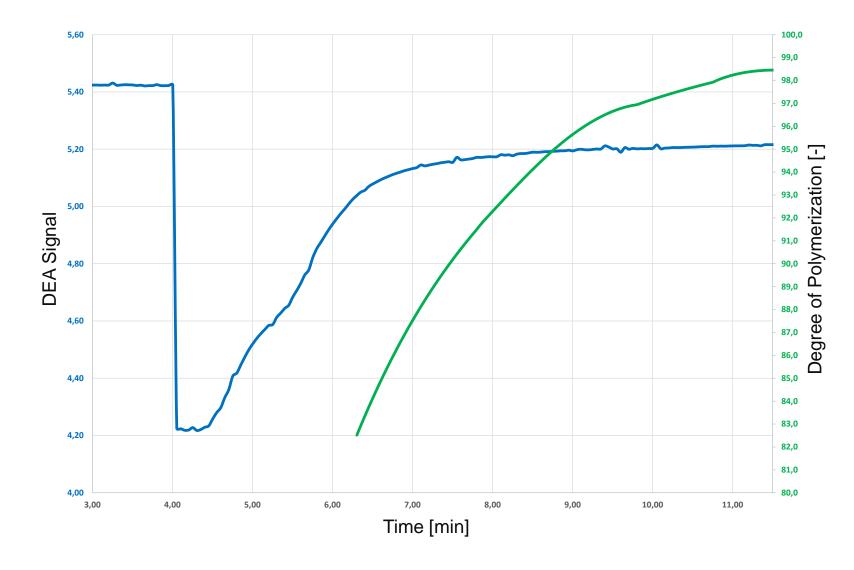
sensXPERT Use Case:

T-RTM FOR AUTOMOTIVE COMPOSITE BATTERY ENCLOSURE

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Real-Time Process Transparency.

- Actively control and measure degree of polymerization
- Eliminate scrap from premature demolding
- Reduce cycle time



RESULTS OF sensXPERT[®]





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